

Product Change Notification - SYST-05QUXF083

Date: 06 Dec 2013

Product Category: 8-bit Microcontrollers

Affected CPNs:  

Notification subject: ERRATA - PIC18F66K80 Family Silicon/Data Sheet Errata Errata Document Revision

Notification text: SYST-05QUXF083

Microchip has released a new DeviceDoc for the PIC18F66K80 Family Silicon/Data Sheet Errata of devices. If you are using one of these devices please read the document located at [PIC18F66K80 Family Silicon/Data Sheet Errata](#).

Notification Status: Final

Description of Change: 1. Added MPLAB X IDE; 2. Updated silicon issue 1 (Analog-to-Digital Converter); 3. Added silicon issue 11 (Primary Oscillator); 4. Other minor corrections; 5. Data Sheet Clarifications: Added Module 7 (Electrical Characteristics) and Module 8 (A/D Converter).

Impacts to Data Sheet: None

Reason for Change: To Improve Productivity

Change Implementation Status: Complete

Date Document Changes Effective: 06 Dec 2013

NOTE: Please be advised that this is a change to the document only the product

has not been changed..

Markings to Distinguish Revised from Unrevised Devices:N/A

Attachment(s): [PIC18F66K80 Family Silicon/Data Sheet Errata](#)

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Affected Catalog Part Numbers (CPN)

PIC18F66K80T-ICE/PT
PIC18F66K80T-I/PTVAO
PIC18F66K80T-I/PT
PIC18F66K80T-I/MR
PIC18F66K80T-E/PT
PIC18F66K80-ICE/PT
PIC18F66K80-I/PTVAO
PIC18F66K80-I/PTREL
PIC18F66K80-I/PT
PIC18F66K80-I/MR
PIC18F66K80-H/PT
PIC18F66K80-H/MR
PIC18F66K80-E/PT
PIC18F66K80-E/MR
PIC18F46K80T-I/PTVAO
PIC18F46K80T-I/PTV10
PIC18F46K80T-I/PT
PIC18F46K80T-I/ML
PIC18F46K80T-E/PT
PIC18F46K80T-E/ML
PIC18F46K80-I/PT
PIC18F46K80-I/P
PIC18F46K80-I/ML
PIC18F46K80-H/PT
PIC18F46K80-H/ML
PIC18F46K80-E/PT
PIC18F46K80-E/P
PIC18F46K80-E/ML
PIC18F45K80T-I/PTV12
PIC18F26K80T-I/SSVAO
PIC18F26K80T-I/SSV07
PIC18F26K80T-I/SS
PIC18F26K80T-I/SO
PIC18F26K80T-I/MM023
PIC18F26K80T-I/MM022
PIC18F26K80T-I/MM020
PIC18F26K80T-I/MM
PIC18F26K80T-H/SSV11
PIC18F26K80T-E/SSVAO
PIC18F26K80T-E/SSV14
PIC18F26K80T-E/SSV06
PIC18F26K80T-E/SS
PIC18F26K80T-E/SO
PIC18F26K80T-E/MMV09
PIC18F26K80T-E/MMV05
PIC18F26K80T-E/MMV01
PIC18F26K80T-E/MM

PIC18F26K80-I/SSVAO
PIC18F26K80-I/SSV15
PIC18F26K80-I/SS
PIC18F26K80-I/SPREL
PIC18F26K80-I/SP
PIC18F26K80-I/SO
PIC18F26K80-I/MM020
PIC18F26K80-I/MM
PIC18F26K80-H/SSV11
PIC18F26K80-H/SS
PIC18F26K80-H/MM
PIC18F26K80-E/SSVAO
PIC18F26K80-E/SSV06
PIC18F26K80-E/SS
PIC18F26K80-E/SP
PIC18F26K80-E/SO
PIC18F26K80-E/MM
PIC18F45K80T-I/PTVAO
PIC18F45K80T-I/PT021
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PIC18F45K80-I/PTVAO
PIC18F45K80-I/PT
PIC18F45K80-I/P
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PIC18F45K80-H/PT
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PIC18F45K80-E/PT
PIC18F45K80-E/P
PIC18F45K80-E/ML
PIC18F25K80T-I/SSVAO
PIC18F25K80T-I/SSV13
PIC18F25K80T-I/SS
PIC18F25K80T-I/SO
PIC18F25K80T-I/MM
PIC18F25K80T-H/SSV03
PIC18F25K80T-E/SSV02
PIC18F25K80T-E/SS
PIC18F25K80T-E/SO
PIC18F25K80T-E/MMVAO
PIC18F25K80T-E/MMV08
PIC18F25K80T-E/MMV04
PIC18F25K80T-E/MM
PIC18F25K80-I/SSVAO
PIC18F25K80-I/SS
PIC18F25K80-I/SP
PIC18F25K80-I/SOVAO
PIC18F25K80-I/SO

PIC18F25K80-I/MM
PIC18F25K80-H/SSV03
PIC18F25K80-H/SS
PIC18F25K80-H/MM
PIC18F25K80-E/SSVAO
PIC18F25K80-E/SSV02
PIC18F25K80-E/SS
PIC18F25K80-E/SP
PIC18F25K80-E/SO
PIC18F25K80-E/MM
PIC18F65K80T-I/PTVAO
PIC18F65K80T-I/PT
PIC18F65K80T-I/MR
PIC18F65K80T-E/PT
PIC18F65K80-I/PTVAO
PIC18F65K80-I/PT
PIC18F65K80-I/MR
PIC18F65K80-H/PT
PIC18F65K80-H/MR
PIC18F65K80-E/PT
PIC18F65K80-E/MR

PIC18F66K80 Family Silicon Errata and Data Sheet Clarification

The PIC18F66K80 family devices that you have received conform functionally to the current Device Data Sheet (DS39977F), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in [Table 1](#). The silicon issues are summarized in [Table 2](#).


The errata described in this document will be addressed in future revisions of the PIC18F66K80 silicon.

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated in the last column of [Table 2](#) apply to the current silicon revision (**A4**).

Data Sheet clarifications and corrections start on [page 8](#), following the discussion of silicon issues.

The silicon revision level can be identified using the current version of MPLAB® IDE and Microchip's programmers, debuggers and emulation tools, which are available at the Microchip corporate web site (www.microchip.com).

For example, to identify the silicon revision level using MPLAB IDE in conjunction with a hardware debugger:

1. Using the appropriate interface, connect the device to the hardware debugger.
2. Open an MPLAB IDE project.
3. Configure the MPLAB IDE project for the appropriate device and hardware debugger.
4. Based on the version of MPLAB IDE you are using, do one of the following:
 - a) For MPLAB IDE 8, select *Programmer > Reconnect*.
 - b) For MPLAB X IDE, select *Window > Dashboard* and click the Refresh Debug Tool Status icon ().
5. Depending on the development tool used, the part number and Device Revision ID value appear in the Output window.

Note: If you are unable to extract the silicon revision level, please contact your local Microchip sales office for assistance.

The DEVREV values for the various PIC18F66K80 silicon revisions are shown in [Table 1](#).

TABLE 1: SILICON DEVREV VALUES

Part Number	Device ID ⁽¹⁾	Revision ID for Silicon Revision ⁽²⁾		
		A2	A3	A4
PIC18F66K80	60E0	2h	3h	4h
PIC18F65K80	6140			
PIC18F46K80	6100			
PIC18F45K80	6160			
PIC18F26K80	6120			
PIC18F25K80	6180			
PIC18LF66K80	61C0			
PIC18LF65K80	6220			
PIC18LF46K80	61E0			
PIC18LF45K80	6240			
PIC18LF26K80	6200			
PIC18LF25K80	6260			

Note 1: The Device IDs (DEVID and DEVREV) are located at the last two implemented addresses of configuration memory space. They are shown in hexadecimal in the format, "DEVID DEVREV".

2: Refer to the "PIC18FXXK80 Flash Microcontroller Programming Specification" (DS39972) for detailed information on Device and Revision IDs for your specific device.

PIC18F66K80

TABLE 2: SILICON ISSUE SUMMARY

Module	Feature	Item Number	Issue Summary	Affected Revisions ⁽¹⁾		
				A2	A3	A4
Analog-to-Digital Converter (A/D)	A/D Performance	1.	The 12-bit A/D performance is outside of data sheet's A/D Converter specifications.	X	X	X
EUSART	Synchronous Transmit	2.	When using the Synchronous Transmit mode, transmitted data may become corrupted if using the TXxIF bit to determine when to load the TXREGx register.	X		
ECCP	Auto-Shutdown	3.	The tri-state setting of the auto-shutdown feature in the enhanced PWM will not successfully drive the pin to tri-state.	X	X	X
ECAN	CAN Clock Source Selection	4.	CLKSEL bit in the CIOCON register is modifiable while the ECAN module is active.	X		
Ultra Low-Power Sleep	Sleep Entry	5.	Entering Ultra Low-Power Sleep mode by setting RETEN = 0 and SRETEN = 1, will cause the part to not be programmable through ICSP™.	X		
IPD and IDD	Maximum Limit	6.	Maximum current limits may be higher than specified in Table 31-2 of the data sheet.	X		
Reset (BOR)	Enable/Disable	7.	An unexpected Reset may occur if the Brown-out Reset module (BOR) is disabled and then re-enabled, when the High/Low-Voltage Detection module (HLVD) is not enabled (HLVDCON<4> = 0).	X	X	X
ECAN	EWIN	8.	The enhanced window address feature, EWIN<4:0>, in the ECANCON register, will not move the BnCON 0≤n≤5 registers into the access window of RAM.	X		
MCLRE	Master Clear Enable	9.	The Master Clear pin will not be readable when MCLRE is set to off for all 28-pin part variants (PIC18F2XK80).	X	X	X
Timer1/Timer3	Gated Enable	10.	Timer1 and Timer3 gate control will not function up to the speed of Fosc when the TxCON is set to the system clock (TxCON<7:6> = 01).	X	X	
Primary Oscillator	XT Mode	11.	XT Primary Oscillator mode does not reliably function when the driving crystals are above 3 MHz.	X	X	X

Note 1: Only those issues indicated in the last column apply to the current silicon revision.

Silicon Errata Issues

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated by the shaded column in the following tables apply to the current silicon revision (**A4**).

the 12-bit A/D performance in their application using the suggested work around below. See [Table 3](#) for guidance specifications.

The 12-bit A/D issues will be fixed in future revisions of this part. Reduced bit resolution specifications can be derived by dividing, as appropriate. For instance, 10-bit guidance is obtained by dividing the parameters in [Table 3](#) by four.

1. Module: Analog-to-Digital Converter (A/D)

The 12-bit A/D performance is outside of the data sheet's A/D Converter specifications. When used as a 12-bit A/D, the possible issues are: high offset error, up to a maximum of ± 25 LSBs at 25°C, ± 30 LSBs at 85°C, 125°C and -40°C; high DNL error, up to a maximum of +6.0/-4.0 LSBs; and multiple missing codes, up to a maximum of twenty. Users should evaluate

A/D Offset

The A/D may have high offset error, up to a maximum of ± 25 LSBs; it can be used if the A/D is calibrated for the offset.

Work around

Calibrate for offset in Single-Ended mode by connecting A/D +ve input to ground and taking the A/D reading. This will be the offset of the device and can be used to compensate for the subsequent A/D readings on the actual inputs.

TABLE 3: A/D CONVERTER CHARACTERISTICS

Param No.	Sym.	Characteristic	Min.	Typ.	Max.	Units	Conditions
A01	NR	Resolution	—	—	12	bit	$\Delta V_{REF} \geq 5.0V$
A03	EIL	Integral Linearity Error	—	—	± 10.0	LSb	$\Delta V_{REF} \geq 5.0V$
A04	EDL	Differential Linearity Error	—	—	+6.0/-4.0	LSb	$\Delta V_{REF} \geq 5.0V$
A06	EOFF	Offset Error	—	—	± 25 ± 30	LSb	$\Delta V_{REF} \geq 5.0V$, TEMP = 25°C TEMP $\geq 85^\circ C$, -40°C
A07	EGN	Gain Error	—	—	± 15	LSb	$\Delta V_{REF} \geq 5.0V$
A10	—	Monotonicity ⁽¹⁾	—				$V_{SS} \leq V_{AIN} \leq V_{REF}$
A20	ΔV_{REF}	Reference Voltage Range ($V_{REFH} - V_{REFL}$)	3	—	$AV_{DD} - AV_{SS}$	V	
A21	V_{REFH}	Reference Voltage High	$AV_{SS} + 3.0V$	—	$AV_{DD} + 0.3V$	V	
A22	V_{REFL}	Reference Voltage Low	$AV_{SS} - 0.3V$	—	$AV_{DD} - 3.0V$	V	
A25	V_{AIN}	Analog Input Voltage	V_{REFL}	—	V_{REFH}	V	

Note 1: The A/D conversion result never decreases with an increase in the input voltage.

Affected Silicon Revisions

A2	A3	A4					
X	X	X					

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2. Module: EUSART

In Synchronous Transmit mode, data may be corrupted if using the TXxIF bit to determine when to load the TXREGx register. One or more of the intended transmit messages may be incorrect.

Work around

A fixed delay added before loading the TXREGx may not be a reliable work around. When loading the TXREGx, check that the TRMT bit inside of the TXSTAx register is set instead of checking the TXxIF bit. The following code can be used:

```
while(!TXSTAxbits.TRMT);  
// wait to load TXREGx until TRMT is set
```

Affected Silicon Revisions

A2	A3	A4					
X							

3. Module: ECCP

The tri-state setting of the auto-shutdown feature, in the enhanced PWM, will not successfully drive the pin to tri-state. The pin will remain an output and should not be driven externally. All tri-state settings will be affected.

Work around

Use one of the other two auto-shutdown states available, as outlined in the data sheet.

Affected Silicon Revisions

A2	A3	A4					
X	X	X					

4. Module: ECAN

The CLKSEL bit in the CIOCON register remains modifiable while the ECAN module is not in Configuration mode. Accidental state changes of this bit will result in immediate bit clock changes that will affect all nodes on the bus.

Work around

While the ECAN module is in Run mode, do not modify the state of the CLKSEL bit in the CIOCON register unless the CAN module is first changed into Configuration mode.

Affected Silicon Revisions

A2	A3	A4					
X							

5. Module: Ultra Low-Power Sleep

Entering Ultra Low-Power Sleep mode by setting `RETEN = 0` and `SRETEN = 1` will cause the part to not be programmable through ICSP. This issue occurs when the `RETEN` fuse bit in `CONFIG1L<0>` is cleared to '0', the `SRETEN` bit in the `WDTCON` register is set to '1' and a `SLEEP` instruction is executed within the first 350 μ s of code execution. This happens after a Reset event, causing the part to enter Ultra Low-Power Sleep mode.

Work around

Use normal Sleep and Low-Power Sleep modes only, or on any Reset, ensure that at least 350 μ s passes before executing a `SLEEP` instruction when ULP is enabled. To ensure the Ultra Low-Power Sleep mode is not enabled, the `RETEN` fuse bit in `CONFIG1L<0>` should be set to a '1' and the `SRETEN` bit in the `WDTCON` register should be cleared to a '0'. The following code can be used:

```
//This will ensure the RETEN fuse is set to 1  
#pragma config RETEN = OFF  
//This will ensure the SRETEN bit is 0  
WDTCONbits.SRETEN = 0;
```

If the Ultra Low-Power Sleep mode is needed, then the user must ensure that the minimum time, before the first `SLEEP` instruction is executed, is greater than 350 μ s.

Affected Silicon Revisions

A2	A3	A4					
X							

6. Module: IPD and IDD

The IPD and IDD limits do not match the data sheet. The IPD values, shown in **bold** in [Section 31.2 “DC Characteristics: Power-Down and Supply Current PIC18F66K80 Family \(Industrial/Extended\)”](#) (below), reflect the updated silicon maximum limits.

All IDD maximum limits will equal 2.8 times the value listed in the data sheet.

Affected Silicon Revisions

A2	A3	A4					
X							

31.2 DC Characteristics: Power-Down and Supply Current PIC18F66K80 Family (Industrial/Extended)

PIC18F66K80 (Industrial/Extended)		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Device	Typ.	Max.	Units	Conditions	
Power-Down Current (IPD) ⁽¹⁾						
PIC18LFXXK80		0.008	7	μA	-40°C	$V_{DD} = 1.8\text{V}^{(4)}$ (Sleep mode) Regulator Disabled
		0.013	7	μA	$+25^{\circ}\text{C}$	
		0.035	9	μA	$+60^{\circ}\text{C}$	
		0.218	10	μA	$+85^{\circ}\text{C}$	
		3	12	μA	$\pm 125^{\circ}\text{C}$	
PIC18LFXXK80		0.014	8	μA	-40°C	$V_{DD} = 3.3\text{V}^{(4)}$ (Sleep mode) Regulator Disabled
		0.034	8	μA	$+25^{\circ}\text{C}$	
		0.092	9	μA	$+60^{\circ}\text{C}$	
		0.312	10	μA	$+85^{\circ}\text{C}$	
		4	16	μA	$\pm 125^{\circ}\text{C}$	
PIC18FXXXK80		0.2	9	μA	-40°C	$V_{DD} = 3.3\text{V}$ (Sleep mode) Regulator Enabled
		0.23	9	μA	$+25^{\circ}\text{C}$	
		0.32	10	μA	$+60^{\circ}\text{C}$	
		0.51	11	μA	$+85^{\circ}\text{C}$	
		5	18	μA	$\pm 125^{\circ}\text{C}$	
PIC18FXXXK80		0.22	10	μA	-40°C	$V_{DD} = 5\text{V}^{(5)}$ (Sleep mode) Regulator Enabled
		0.24	10	μA	$+25^{\circ}\text{C}$	
		0.34	11	μA	$+60^{\circ}\text{C}$	
		0.54	12	μA	$+85^{\circ}\text{C}$	
		5	20	μA	$\pm 125^{\circ}\text{C}$	

Legend: Shading of rows is to assist in readability of the table.

- Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD} or V_{SS} , and all features that add delta current disabled (such as WDT, SOSC oscillator, BOR, etc.).
- 2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
 $\text{OSC1} = \text{external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to } V_{DD};$
 $\text{MCLR} = V_{DD}; \text{ WDT enabled/disabled as specified.}$
- 3: Standard, low-cost 32 kHz crystals have an operating temperature range of -10°C to $+70^{\circ}\text{C}$. Extended temperature crystals are available at a much higher cost.
- 4: For LF devices, $\text{RETEN} (\text{CONFIG1L}\langle 0 \rangle) = 1$.
- 5: For F devices, $\text{SRETEN} (\text{WDTCON}\langle 4 \rangle) = 1$ and $\text{RETEN} (\text{CONFIG1L}\langle 0 \rangle) = 0$.

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7. Module: Reset (BOR)

An unexpected Reset may occur if the Brown-out Reset module (BOR) is disabled, and then re-enabled, when the High/Low-Voltage Detection module (HLVD) is not enabled (HLVDCON<4> = 0). This issue affects BOR modes: BOREN<1:0> = 10 and BOREN<1:0> = 01. In both of these modes, if the BOR module is re-enabled while the device is active, unexpected Resets may be generated.

Work around

If BOR is required and power consumption is not an issue, use BOREN<1:0> = 11. For BOREN<1:0> = 10 mode, either switch to BOREN<1:0> = 11 mode or enable the HLVD (HLVDCON<4> = 1) prior to entering Sleep. If power consumption is an issue and low power is desired, do not use BOREN<1:0> = 10 mode. Instead, use BOREN<1:0> = 01 and follow the steps below when entering and exiting Sleep.

1. Disable BOR by clearing SBOREN (RCON<6> = 0).
`WDTCONbits.SBOREN = 0;`
2. Enter Sleep mode (if desired).
`Sleep();`
3. After exiting Sleep mode (if entered), enable the HLVD bit (HLVDCON<4> = 1).
`HLVDCONbits.HLV DEN = 1;`
4. Wait for the internal reference voltage (TIRVST) to stabilize (typically 25 μs).
`while(!HLVDCONbits.IRVST);`
5. Re-enable BOR by setting SBOREN (RCON<6> = 1).
`WDTCONbits.SBOREN = 1;`
6. Disable the HLVD by clearing HLVDEN (HLVDCON<4> = 0).
`HLVDCONbits.HLV DEN = 0;`

Affected Silicon Revisions

A2	A3	A4					
X	X	X					

8. Module: ECAN

The enhanced window address feature, EWIN<4:0>, in the ECANCON register, will not move the BnCON 0≤n≤5 registers into the access window of RAM. The rest of the registers in B0 through B5 will be transferred into the access bank successfully. This feature is only available in Mode 1 and Mode 2; Mode 0 applications will not be affected.

Work around

1. Set the ECANCON register EWIN bits to the desired buffer.
`ECANCONbits.EWIN = Buffer_Selection;`
2. Decode the desired buffer to each individual Buffer Control register, BnCON 0≤n≤5.
`switch (Buffer_Selection)`
{
//EWIN code for Buffer B0
case 18:
 break;

//EWIN code for Buffer B5
case 23:
 break;
default:
 break;
}
3. Process information in the selected buffer control register. Note that the BnCON 0≤n≤5 Control registers can be set up for either transmit or receive operations.
case 18:
 //Save B0CON and clear flags being processed
 temp = B0CON;
 //clear any flags
 break;
4. Continue processing the rest of the buffer in the windowed location.

Affected Silicon Revisions

A2	A3	A4					
X							

9. Module: MCLRE

The Master Clear pin will not be readable when MCLRE is set to off for all 28-pin part variants (PIC18F2XK80). When the MCLRE bit, CONFIG3H<7>, is cleared on 28-pin devices, the MCLR pin will be disabled but input data will not be available on RE3.

Work around

None.

Affected Silicon Revisions

A2	A3	A4					
X	X	X					

10. Module: Timer1/Timer3

Timer1 and Timer3 gate control will not function up to the speed of Fosc when the TxCON is set to the system clock (TxCON<7:6> = 01). Results will always be at the resolution of Fosc/4, although the internal Fosc has been selected as the clock source.

Work around

Use the external clock input pin setting, TxCON<7:6> = 10 and TxCON<3> = 0.

Affected Silicon Revisions

A2	A3	A4					
X	X						

11. Module: Primary Oscillator (XT Mode)

On some parts, using the XT oscillator at the top end of its specified frequency range (3.0 - 4.0 MHz) may cause the part to cease driving the oscillator.

Work around

Use the XT mode only for frequencies lower than 3.0 MHz.

Use the HS mode if frequencies greater than 4.0 MHz on a crystal oscillator are required.

Affected Silicon Revisions

A2	A3	A4					
X	X	X					

PIC18F66K80

Data Sheet Clarifications

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS39977F):

Note: Corrections are shown in bold . Where possible, the original bold text formatting has been removed for clarity.

1. Module: RXFCON Registers

Table 6-1 on page 116 of the Data Sheet should show the following register addresses:

E47h-RXFCON1

E46h-RXFCON0

2. Module: RXFCON Registers

Table 6-2 on page 125 of the Data Sheet should show the following register addresses:

E47h-RXFCON1

E46h-RXFCON0

3. Module: Listen Only Mode

Page 441, **Section 27.3.4 “Listen Only Mode”** will be revised to:

Listen Only mode provides a means for the PIC18F66K80 family devices to receive all messages, including messages with errors. This mode can be used for bus monitor applications or for detecting the baud rate in ‘hot plugging’ situations. For Auto-Baud Detection, it is necessary that there are at least two other nodes which are communicating with each other. The baud rate can be detected empirically by testing different values until valid messages are received. The Listen Only mode is a silent mode, meaning no messages will be transmitted while in this state, including error flags or Acknowledge signals. **In Listen Only mode, both valid and invalid messages will be received regardless of RXMn bit settings. The filters and masks can still be used to allow only particular valid messages to be loaded into the Receive registers, or the filter masks can be set to all zeros to allow a message with any identifier to pass. All invalid messages will be received in this mode, regardless of filters and masks or RXMn Receive Buffer mode bits.** The error counters are reset and deactivated in this state. The Listen Only mode is activated by setting the mode request bits in the CANCON register.

4. Module: A/D Converter Characteristics

The values in [Table 31-25](#) reflect the updated A/D Converter Characteristics. The new information is shown in **bold text**.

TABLE 31-25: A/D CONVERTER CHARACTERISTICS: PIC18F66K80 (INDUSTRIAL/EXTENDED)

Param No.	Sym.	Characteristic	Min.	Typ.	Max.	Units	Conditions
A01	NR	Resolution	—	—	12	bit	$\Delta V_{REF} \geq 5.0V$
A03	EIL	Integral Linearity Error	—	$<\pm 1$	± 6.0	LSB	$\Delta V_{REF} \geq 5.0V$
A04	EDL	Differential Linearity Error	—	$<\pm 1$	$+3.0/-1.0$	LSB	$\Delta V_{REF} \geq 5.0V$
A06	EOFF	Offset Error	—	$<\pm 1$	± 9.0	LSB	$\Delta V_{REF} \geq 5.0V$
A07	EGN	Gain Error	—	$<\pm 1$	± 8.0	LSB	$\Delta V_{REF} \geq 5.0V$
A10	—	Monotonicity⁽¹⁾	—			—	$V_{SS} \leq V_{AIN} \leq V_{REF}$
A20	ΔV_{REF}	Reference Voltage Range ($V_{REFH} - V_{REFL}$)	3	—	$V_{DD} - V_{SS}$	V	For 12-bit resolution
A21	V_{REFH}	Reference Voltage High	$AV_{SS} + 3.0V$	—	$AV_{DD} + 0.3V$	V	For 12-bit resolution
A22	V_{REFL}	Reference Voltage Low	$AV_{SS} - 0.3V$	—	$AV_{DD} - 3.0V$	V	For 12-bit resolution
A25	V_{AIN}	Analog Input Voltage	V_{REFL}	—	V_{REFH}	V	
A28	AV_{DD}	Analog Supply Voltage	$V_{DD} - 0.3$	—	$V_{DD} + 0.3$	V	
A29	AV_{SS}	Analog Supply Voltage	$V_{SS} - 0.3$	—	$V_{SS} + 0.3$	V	
A30	Z_{AIN}	Recommended Impedance of Analog Voltage Source	—	—	2.5	k Ω	
A50	I_{REF}	V_{REF} Input Current ⁽²⁾	—	—	5 150	μA μA	During V_{AIN} acquisition. During A/D conversion cycle.

Note 1: The A/D conversion result never decreases with an increase in the input voltage.

2: V_{REFH} current is from the RA3/AN3/ V_{REF+} pin or V_{DD} , whichever is selected as the V_{REFH} source. V_{REFL} current is from the RA2/AN2/ V_{REF-}/CV_{REF} pin or V_{SS} , whichever is selected as the V_{REFL} source.

5. Module: HLVD

Note 1 under Register 26-1: HLVDCON, on page 387, should direct to Parameter D420:

Note 1: For the electrical specifications, see Parameter **D420** in Section 31.0 “Electrical Characteristics”.

6. Module: Power-up Timer Period

Table 31-11 on page 572 of the data sheet, **Parameter 33 T_{PWRT}** will be revised to a typical value of **1.0 ms**.

7. Module: Electrical Characteristics

Parameter **D041** in **Section 31.3 “DC Characteristics: PIC18F66K80 Family (Industrial)”** on page 555 of the data sheet lists its minimum value as 0.8. This should be **0.8 V_{DD}** .

8. Module: A/D Converter

Bits 5-4 of Register 23-2: ADCON1 ($VC_{FG}<1:0>$) should have the following note attached:

Note 1: When $CHS<4:0> = 11111$, a $VC_{FG}<1:0>$ value of 10 or 11 is not allowed.

PIC18F66K80

APPENDIX A: DOCUMENT REVISION HISTORY

Rev A Document (2/2011)

Initial release of this document; issued for revision, A2. Includes silicon issues 1 (Analog-to-Digital Converter), 2 (EUSART), 3 (ECCP), 4 (ECAN), 5 (Ultra Low-Power Sleep) and 6 (IPD and IDD).

Rev B Document (4/2011)

Added silicon issues 7 (Reset – BOR) and 8 (ECAN). Added data sheet clarifications 1, 2 (RXFCON Registers) and 3 (Listen Only Mode).

Rev C Document (9/2011)

Added [Table 3](#), 10-Bit A/D Converter Characteristics to silicon issue 1 (Analog-to-Digital Converter). Added silicon issues 9 (MCLRE) and 10 (Timer1/Timer3). Added data sheet clarifications 4 (A/D Converter Characteristics) and 5 (HLVD).

Rev D Document (12/2011)

Added silicon revision A4; includes issues 1 (Analog-to-Digital Converter – A/D), 3 (ECCP), 7 (Reset – BOR) issues 9 (MCLRE). Added data sheet clarification 6 (Power-up Timer Period).

Updated data sheet revision level to “D”. All previous clarifications carried into this revision.

Rev E Document (12/2013)

Added MPLAB X IDE; Updated silicon issue 1 (Analog-to-Digital Converter); Added silicon issue 11 (Primary Oscillator); Other minor corrections;

Data Sheet Clarifications: Added Module 7 (Electrical Characteristics) and Module 8 (A/D Converter).

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